



MYSmart™ Industrial dispensing applications



High-productivity, high precision
Industrial dispensing

MYCRONIC

When passion meets innovation ●

Introducing typical applications

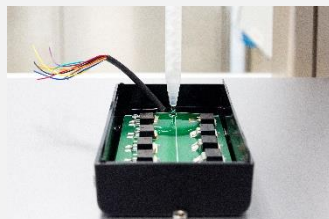
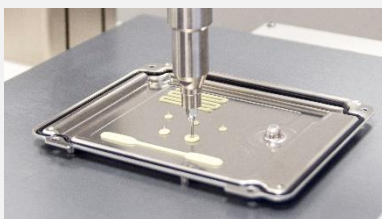
Protect your electronics

Power Electronics

The in-line MYSmart series Industrial dispensers are ideal for medium to high-volume production of industrial / bulk dispensing applications like:

- Thermal Interface Material dispensing
- Casting / potting of electronics
- Bonding of THT components
- Gasketing / Sealing

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- 1 Single component materials
 - 2 Dual component materials
 - 3 Bulk material feed
 - 4 Positive displacement / Volumetric dispensing
 - 5 Progressive Cavity Pumps
 - 6 Heavy duty conveyors
 - 7 XYZ- movement
 - 8 Programmable rotation & tilt

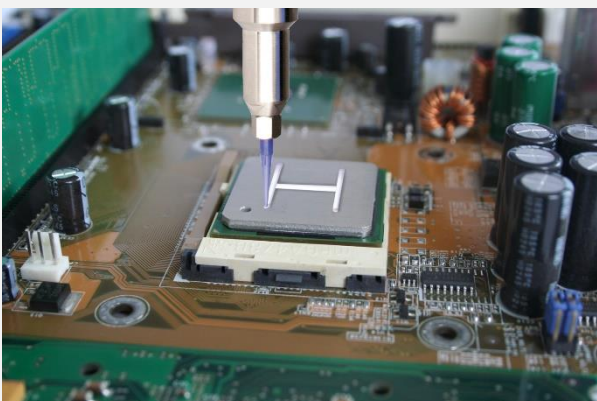
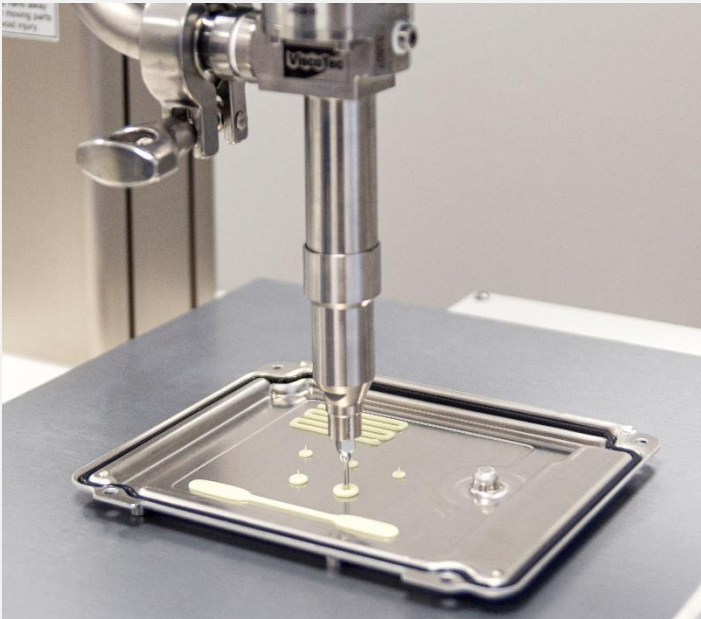


Thermal Interface Material Dispensing

Effective control of heat is an increasing concern among today's electronics device manufacturers and, as products become smaller, the need to dissipate heat effectively will be greater than ever.

Effectively controlling the thermal load will be critical to ensuring long product life cycles and expected reliability.

That is why today's electronics manufacturers are increasingly looking for Thermal Management Solutions.



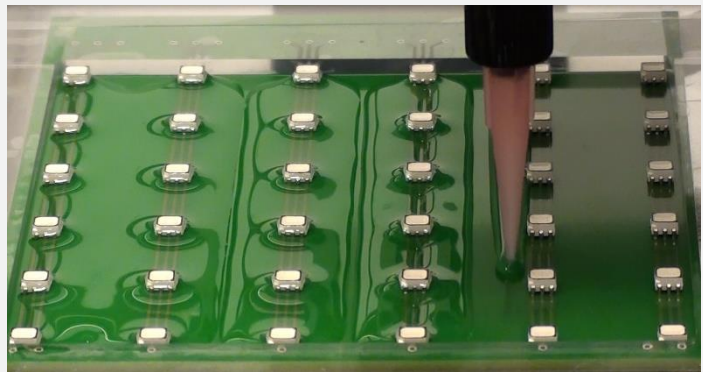
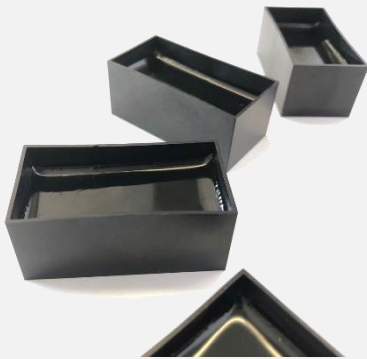
Casting / Potting of electronics

Casting compounds protect and insulate electronics, (sensor technology, lighting electronics etc.) against extreme weather conditions and aggressive media.

Why are electronic components cast?

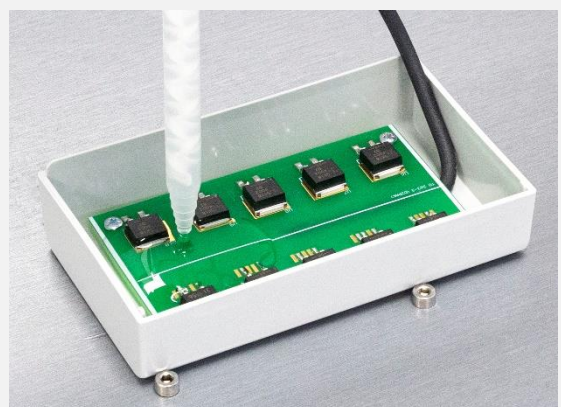
Condensation / moisture

Electronics often come into contact with moist air or even water (rain). Casting / moulding electronic components offers the best possible protection against moisture.



Electrical discharge

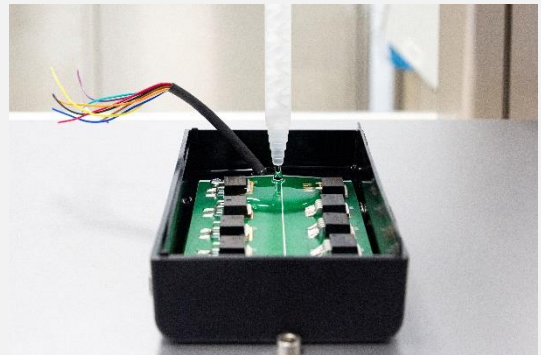
The challenge of placing as many functions as possible on the smallest possible circuit board (PCB), is sometimes not possible from the point of view of electrical discharge. However, the density of the artificial resin, makes it possible to produce a cast circuit board with the required minimum dimensions, and protect it from electrical discharges.



Casting / Potting of electronics (2)

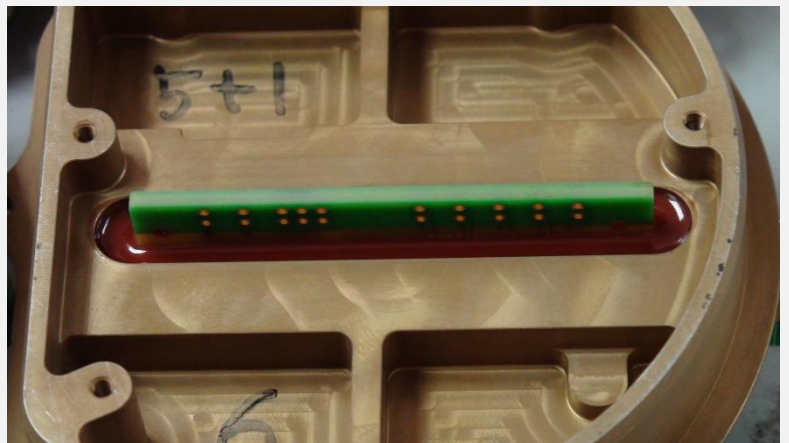
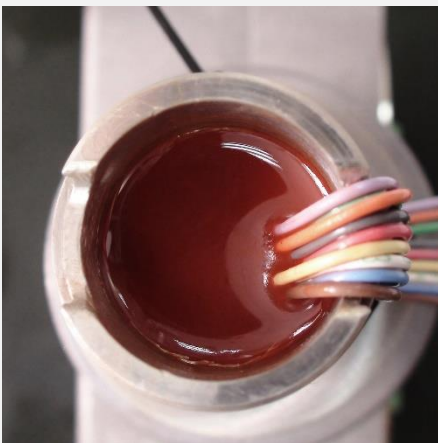
Vibrations / Temperatures

Impacts and extreme temperatures reduce the life span of components, contacts and solder joints. Especially in the automotive industry, electronic components are often exposed to extreme conditions. Our casting process offers the best possible protection of your components against strong vibrations, and makes them resistant to temperatures from -40°C to $+130^{\circ}\text{C}$.



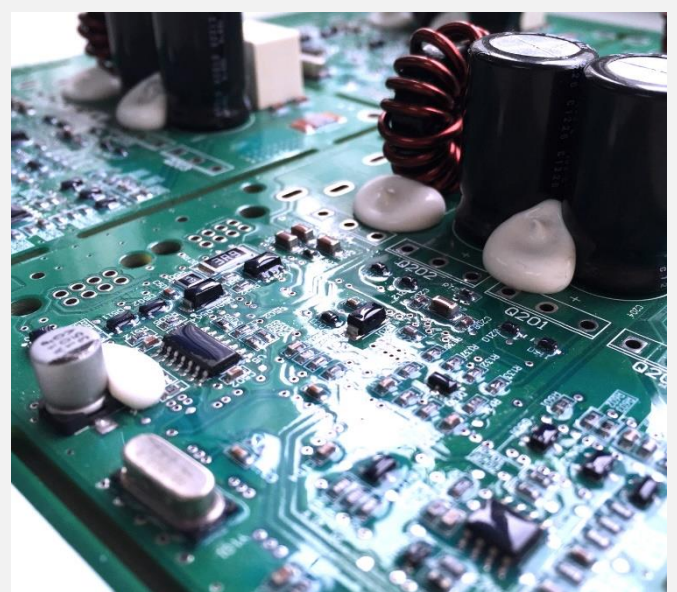
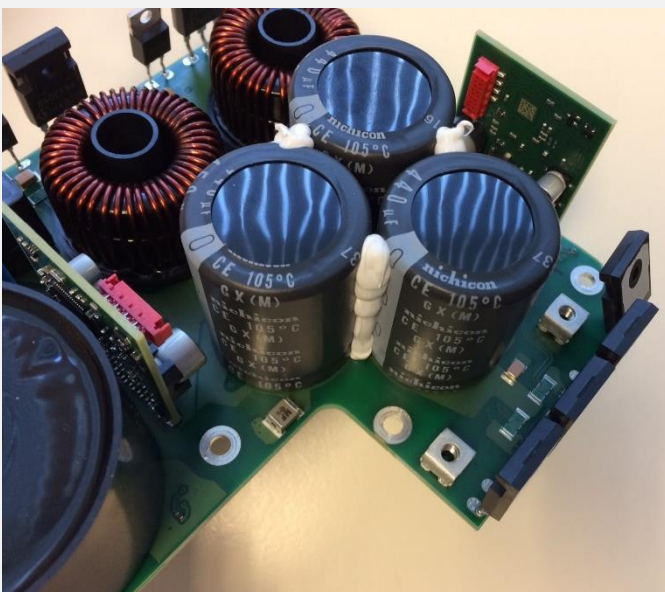
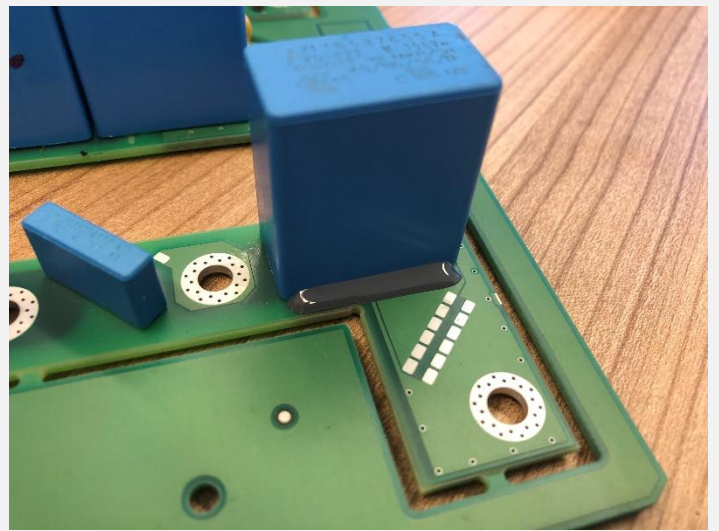
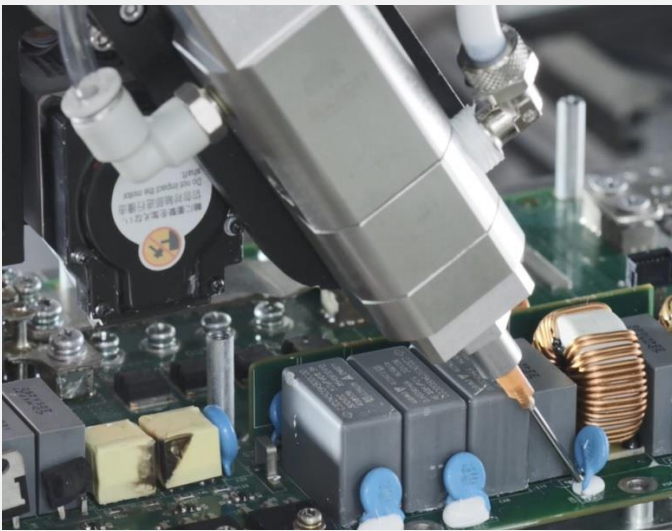
Competition and manipulation

Casting electronic components not only protects your products against incorrect use or certain manipulations, but also the curious gaze of your competitors.



Bonding of THT components

THT components are typically tall components connected to a PCB by wires going through the board. These components are sensitive for mechanical stress. In order to better protect these components single or dual component materials can be dispensed between THT components, or in the collar of these components and the PCB board.



Gasketing / Sealing

Gasket dispensing describes the extrusion of a viscous fluid that upon curing forms an elastomeric seal. After cure, when a mating surface is applied, the joined parts typically meet some requirement for a barrier against liquids or gasses. Commonly referred to as Form In Place gasketing (FIP), this process avoids the cumbersome aspects of handling and placing cut gaskets and affords the flexibility of many variations without having to inventory cut gaskets.

